Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently amended) A flexible matrix array device comprising

a thin film matrix circuit carried on the surface of a flexible substrate

which matrix circuit includes:

semiconductor devices arranged in a regular array and occupying respective~~, discrete,~~ first areas of the substrate, and

pixel electrodes correspondingly coupled to each of the semiconductor devices and occupying respective second areas of the substrate;

wherein

~~selected regions of the substrate away from the areas occupied by the semiconductor devices comprise areas of weakness at which~~ the substrate is configured such that flexing of the substrate occurs more readily at the second areas than at the first areas.

2. (Currently amended) A curved matrix array device comprising

a thin film matrix circuit carried on the surface of a substrate

which matrix circuit includes:

semiconductor devices arranged in a regular array and occupying respective~~, discrete,~~ first areas of the substrate, and

pixel electrodes correspondingly coupled to each of the semiconductor devices and occupying respective second areas of the substrate;

wherein

the substrate is configured such that~~comprises areas of weakness at selected regions away from the semiconductor devices and~~

~~the~~ curvature of the device is accommodated substantially by deformation at the substrate at ~~those regions~~the second areas.

C2

3. (Currently amended) A device according to Claim 1, wherein

the second areas ~~of weakness~~ comprise locally thinner regions of the substrate.

C3

4. (Original) A device according to Claim 3, wherein

the locally thinner regions are formed by selective etching of the substrate.

5. (Original) A device according to Claim 3, wherein

the substrate comprises a laminated structure with at least two layers and in which one layer is patterned to form the locally thinner regions.

C4

6. (Currently amended) A device according to Claim 1, wherein

the second areas ~~of weakness~~ comprise areas of the substrate at which the material of the substrate is rendered less stiff compared with the first areas of the substrate ~~occupied by the semiconductor devices~~.

7. (Currently amended) A device according to ~~any one of Claims~~Claim 1, wherein

the substrate comprises polymer material.

8. (Currently amended) A device according to ~~any one of Claims~~Claim 1, wherein

the second areas ~~of weakness extend as~~include lines ~~of weakness~~that facilitate flexing of the substrate between the first areas of the substrate ~~carrying the semiconductor devices~~.

C5

9. (Currently amended) A device according to Claim 8, wherein

the semiconductor devices are arranged in an array of rows and columns and wherein

the second areas ~~of weakness~~ comprise lines ~~of weakness~~that facilitate flexing of the substrate extending across the array between rows and/or columns of semiconductor devices.

C6 10. (Currently amended) A device according to ~~any one of Claims~~Claim 1, wherein the ~~discrete~~ first areas ~~of the substrate carrying the semiconductor devices~~ are thicker than the ~~remaining~~ second areas of substrate.

C7 11. (Previously amended) A device according to claim 1, wherein the semiconductor devices each comprise a semiconductor film formed into an island.

12. (Previously amended) A device according to claim 1, wherein the semiconductor devices comprises thin film transistors.

C8 13. (Currently amended) A device according to claim 1, wherein the device comprises an active matrix display devices having an array of display pixels ~~and in which each semiconductor device is connected to a respective pixel electrode carried on the substrate~~.

C9 14. (Original) A device according to Claim 13, wherein the device comprises an active matrix liquid crystal display device which includes a further flexible substrate mounted to the substrate carrying the matrix circuit with liquid crystal material disposed between the substrates.

C10 15. (Currently amended) A device according to Claim 14, wherein the further substrate has lines ~~of weakness~~that facilitate flexing formed therein.